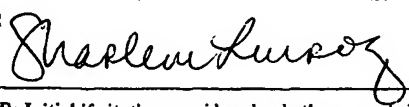
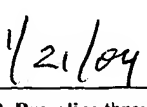
		Docket Number (Optional) UDC-20101	Application Number 10/043,849
		Applicant(s) Michael Stuart Weaver et al.	
		Filing Date 1/10/02	Group Art Unit 2879
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82	6.	Dan Daly et al., "Little Lenses, Major Markets: Microlens Arrays Provide Optical Versatility in a Miniature Package for Communications, Display, and Imaging Application," <i>Photonics Spectra</i> , July 2001, pp. 120-122.	
82	7.	A. N. Safonov et al., "Modification of Polymer Light Emission by Lateral Microstructure," <i>Synthetic Metals</i> , Vol. 116, 2001, pp. 145-148.	
82	8.	Benjamin J. Matterson et al., "Increased Efficiency and Controlled Light Output from a Microstructured Light-Emitting Diode," <i>Advanced Materials</i> , Vol. 13, no. 2, Jan. 16, 2001, pp. 123-127.	
82	9.	G. Gu et al., "High-External-Quantum-Efficiency Organic Light-Emitting Devices," <i>Optics Letters</i> , Vol. 22, no. 6, March 15, 1997, pp. 396-398.	
82	10.	C. F. Madigan et al., "Improvement of Output Coupling Efficiency of Organic Light-Emitting Diodes by Backside Substrate Modification," <i>Applied Physics Letters</i> , Vol., 76, no. 13, March 27, 2000, pp. 1650-1652.	
EXAMINER		DATE CONSIDERED	
			
<p>*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>			

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